

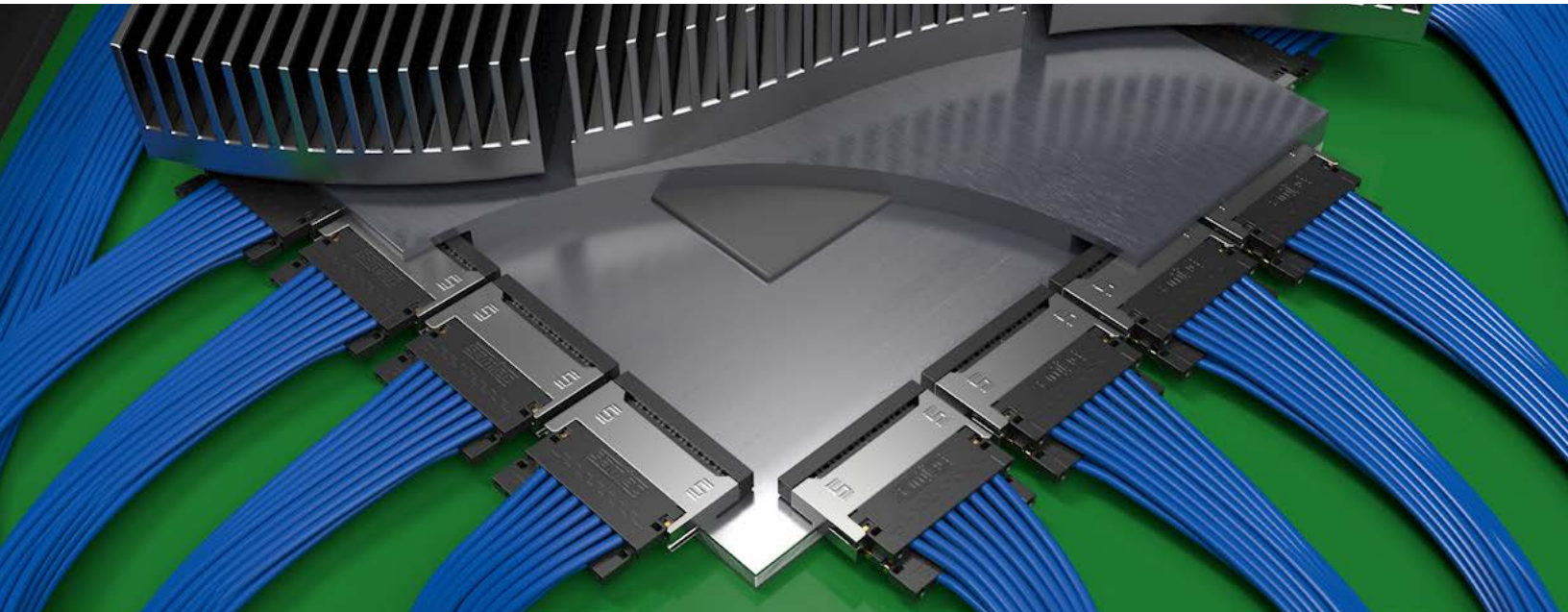


SI-FLY™

| | |
|------------|-------------|
| NRZ | PAM4 |
| 56 Gbps | 112 Gbps |

112 Gbps PAM4, DIRECT CONNECT CABLE TO IC PACKAGE

- Ultra-high density with direct connect to IC package technology
- Eludes the BGA and routes signals directly from the silicon package through a long-reach cable
- Extreme channel performance enabling 25.6 TB aggregate with a path to 51.2 TB
- 112 Gbps PAM4 per lane
- Samtec offers two Direct Connect to IC package solutions: FireFly™ (available now) & Si-Fly™ (in development)



~5X THE REACH, COMPARED TO TRADITIONAL PCB

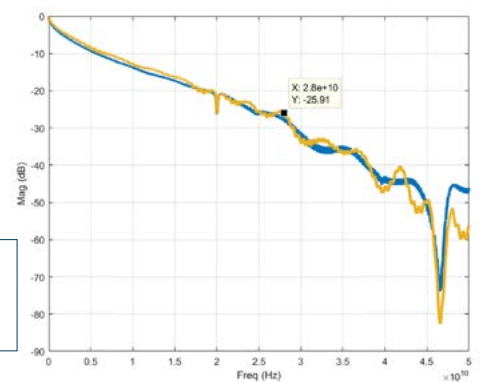


22-INCH REACH
28 dB SPEC

Conventional
PCB Topology

4.5-INCH REACH
28 dB SPEC

S-PARAMETER PLOT



REACH

- 22"; Si-Fly™
- 4.5"; Megtron 7

FULL CHANNEL

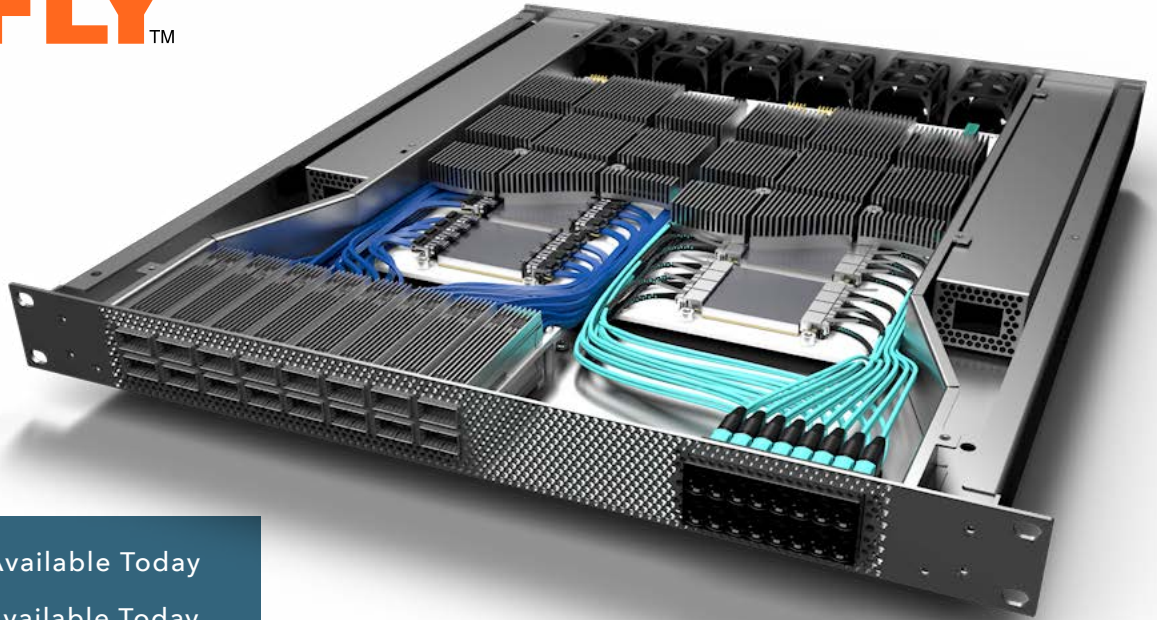
For additional information visit samtec.com/si-fly

© JANUARY 2020, SAMTEC, INC.

SAMTEC DIRECT CONNECT ON-PACKAGE TECHNOLOGY

FIREFLY™

| | |
|------------|------------|
| NRZ | PAM4 |
| 28 Gbps | 56 Gbps |

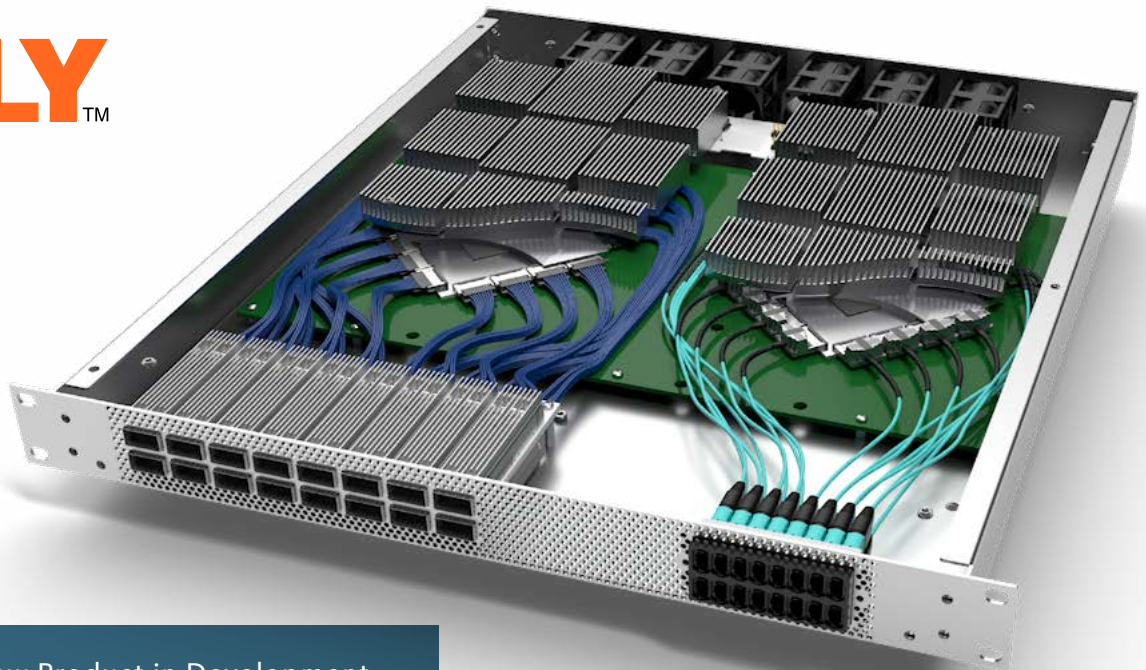


Copper FireFly™ - Available Today

Optical FireFly™ - Available Today

SI-FLY™

| | |
|------------|-------------|
| NRZ | PAM4 |
| 56 Gbps | 112 Gbps |



Copper Si-Fly™ - New Product in Development

Optical Si-Fly™ - Roadmap